

LY-SUG-07

This product is new developed to meet the electronic industry’s growing need for interface materials with greater conformability, solderable on the surface and easier application especially suited for dynamic environment.

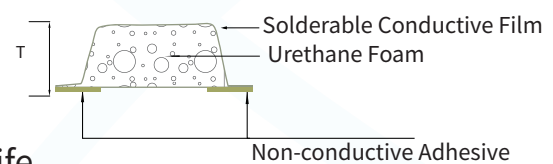
Features

- Solderable on the surface
- Available in multiple thicknesses
- Auto mounting in PCB process
- Enhanced puncture, shear and tear resistance

Benefit

- Easy to apply
- Save the cost
- Customizable
- Extended product’s life especially in dynamic environment

Structure



Specifications

PROPERTIES	DATA	TEST METHOD
Color	Sliver	Visual
Solderable Film	Tinned copper on FCCL	/
Wrapped material	Urethane Foam	/
Thickness of product, mm	0.7±0.1	/
Recommended compression set, %	20 to 40	Internal standard
Flammability Rating	Equivalent to V-1	UL94
Foam Density, kg/m ³	50 ± 5	ASTM D3575
Resistance, ohm/sq @50% compressed	< 0.3	MIL-DTL-83528 modified
Long-term Temperature Range, °C	-40 to 100	Internal standard

The above data is the general value tested in the laboratory environment (23 ± 5°C, 55± 10% R.H.) and does not represent the actual value of each product

Storage and Shelf Life

Shelf life is 6 months after shipment, while stored at 25°C/65% in a sealed bag

Regulation

RoHS & HF Compliant

Disclaimers

Many factors beyond Longyoung’s control and uniquely within user’s knowledge and control can affect the use and performance of a longyoung product in a particular application. As a result, customer is solely responsible for evaluating the product and determining whether it is appropriate and suitable for customer’s application.

